

# SEMIPACK® 3

### Thyristor / Diode Modules

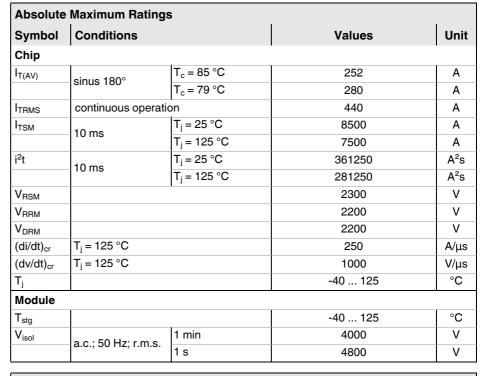
#### **SKKH 280/22 E H4**

#### Features\*

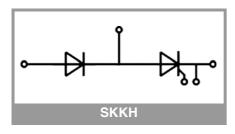
- Heat transfer through aluminum nitride ceramic insulated metal baseplate
- Precious metal pressure contacts for high reliability
- · Thyristor with amplifying gate
- UL recognized, file no. E 63 532

#### **Typical Applications**

- DC motor control (e. g. for machine tools)
- AC motor starters
- Temperature control (e. g. for ovens, chemical processes)
- Professional light dimming (studios, theaters)



Characte	eristics					
Symbol	Conditions	min.	typ.	max.	Unit	
Chip	•					
$V_{T}$	$T_j = 25 ^{\circ}\text{C}, I_T = 750 \text{A}$				1.55	V
$V_{T(TO)}$	T <sub>j</sub> = 125 °C				0.90	V
r <sub>T</sub>	T <sub>j</sub> = 125 °C				0.75	mΩ
$I_{DD};I_{RD}$	$T_j = 125 ^{\circ}\text{C},  V_{DD} = V_{DRM};  V_{RD} = V_{RRM}$				90	mA
t <sub>gd</sub>	$T_j = 25  ^{\circ}C,  I_G = 1  A,  di_G/dt = 1  A/\mu s$			1		μs
t <sub>gr</sub>	V <sub>D</sub> = 0.67 * V <sub>DRM</sub>			2		μs
t <sub>q</sub>	T <sub>j</sub> = 125 °C		50	150	150	μs
I <sub>H</sub>	T <sub>j</sub> = 25 °C			150	500	mA
IL	$T_j = 25 ^{\circ}\text{C},  R_G = 33 \Omega$			300	2000	mA
V <sub>GT</sub>	$T_j = 25$ °C, d.c.		3			V
I <sub>GT</sub>	$T_j = 25$ °C, d.c.		200			mA
$V_{GD}$	$T_j = 125$ °C, d.c.				0.25	V
I <sub>GD</sub>	$T_j = 125$ °C, d.c.				10	mA
$R_{th(j-c)}$	cont.	per chip			0.11	K/W
		per module			0.055	K/W
$R_{th(j-c)}$	sin. 180°	per chip			0.116	K/W
		per module			0.058	K/W
R <sub>th(j-c)</sub>	rec. 120°	per chip			0.13	K/W
		per module			0.065	K/W
Module						
R <sub>th(c-s)</sub>	chip			0.04		K/W
	module			0.02		K/W
Ms	to heatsink M5		4.25		5.75	Nm
Mt	to terminals M8		7.65		10.34	Nm
а					5 * 9.81	m/s²
w				600		g



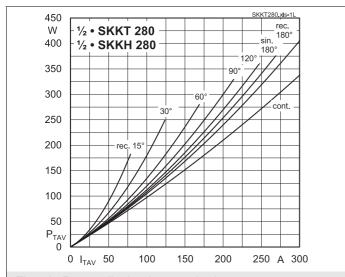


Fig. 1L: Power dissipation per thyristor vs. on-state current

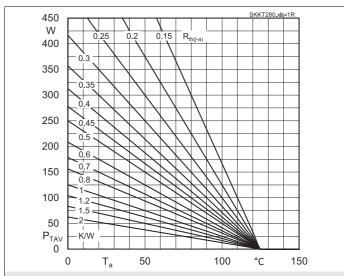


Fig. 1R: Power dissipation per thyristor vs. ambient temperature

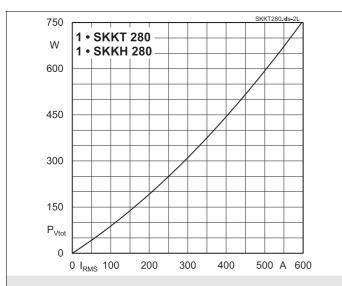


Fig. 2L: Power dissipation of one module vs. rms current

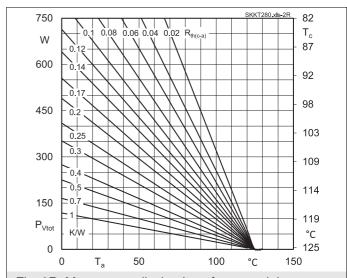


Fig. 2R: Max. power dissipation of one module vs. case temperature

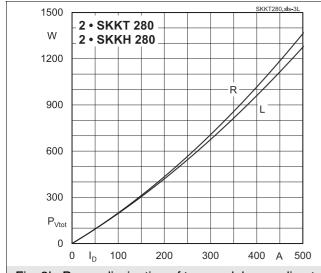


Fig. 3L: Power dissipation of two modules vs. direct current

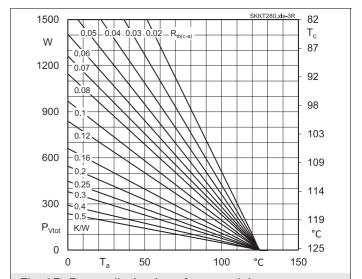


Fig. 3R: Power dissipation of two modules vs. case temperature

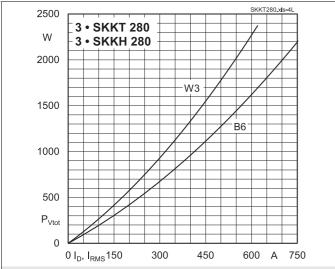


Fig. 4L: Power dissipation of three modules vs. direct and rms current

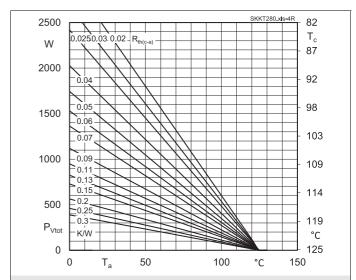


Fig. 4R: Power dissipation of three modules vs. case temperature

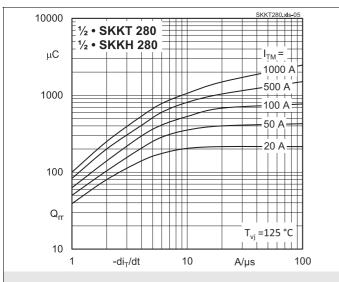


Fig. 5: Recovered charge vs. current decrease

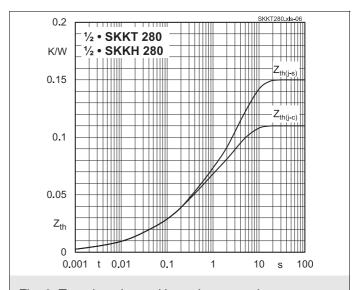


Fig. 6: Transient thermal impedance vs. time

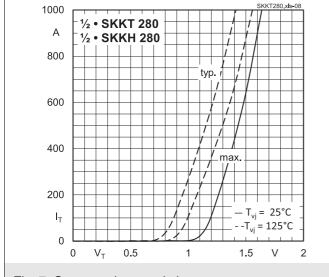


Fig. 7: On-state characteristics

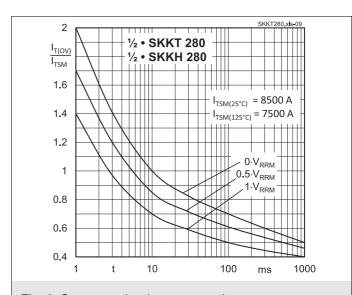


Fig. 8: Surge overload current vs. time

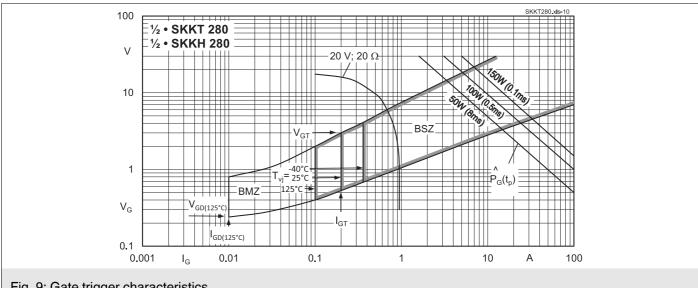
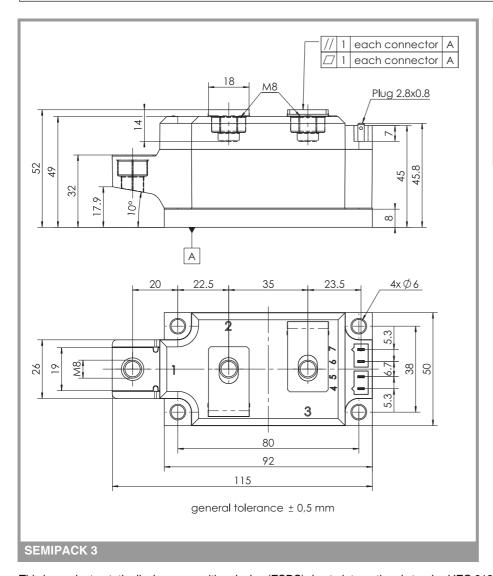
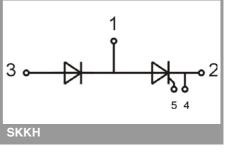


Fig. 9: Gate trigger characteristics





This is an electrostatic discharge sensitive device (ESDS) due to international standard IEC 61340.

#### \*IMPORTANT INFORMATION AND WARNINGS

The specifications of SEMIKRON products may not be considered as guarantee or assurance of product characteristics ("Beschaffenheitsgarantie"). The specifications of SEMIKRON products describe only the usual characteristics of products to be expected in

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